

ABSTRACT OF THE DISCLOSURE

An IC socket for the fine pitch IC package includes a socket body having an opening for guiding the IC package, an insulation base having a plurality of through-holes corresponding to the external terminals of the IC package, the contact pins placed in the through-holes, and a cover member for applying a predetermined pressure to bring the external terminals of the IC package and the contact pins into contact with one another. Each of the contact pins is formed with a first plunger including a terminal portion to be in contact with the external terminal of the IC package, a wider portion whose width is larger than the width of the terminal portion and the shaft whose width is equal to or smaller than the terminal portion, the coil spring, and the second plunger having a U-shape section, to be connected with the contact terminal of external circuit.